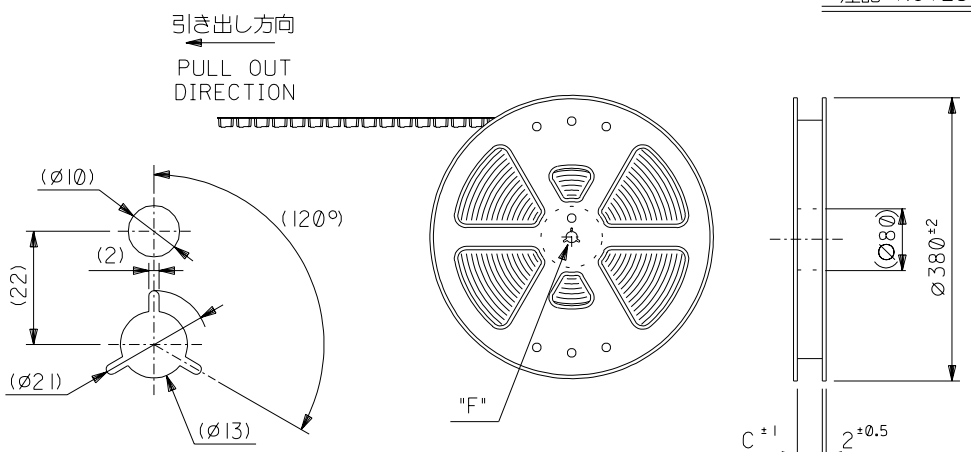
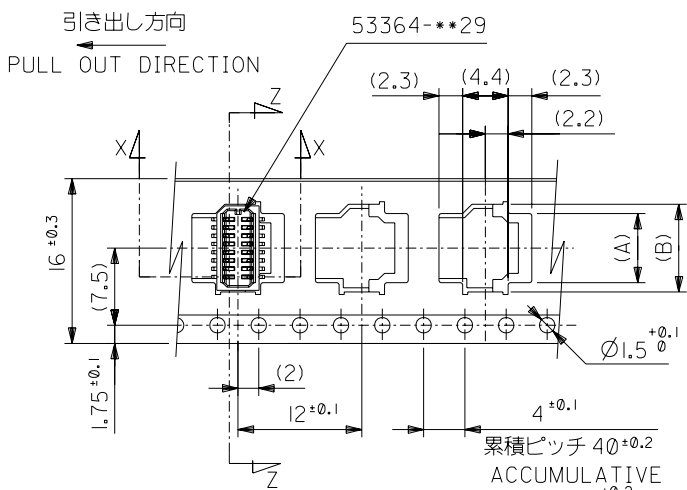
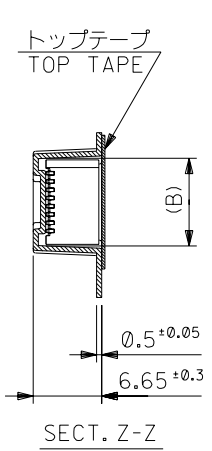


注記 NOTES

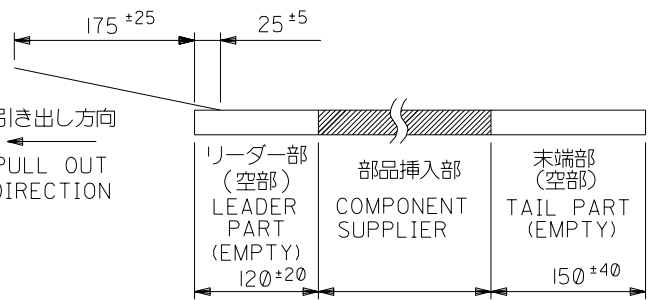
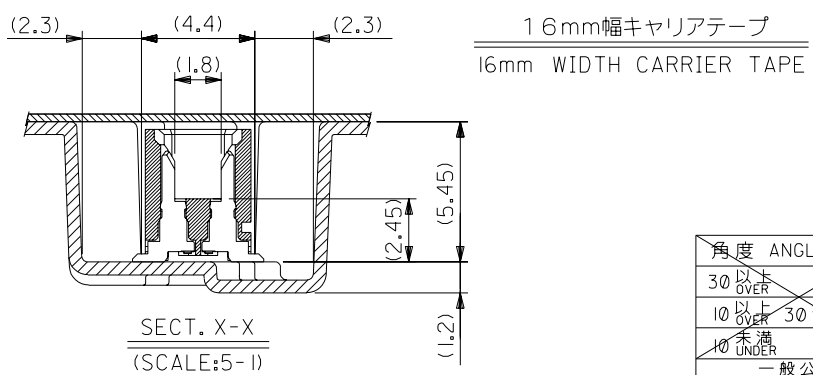
1. 梱包数量：1000個/リール NUMBER OF CONNECTORS:1000PCS/REEL
 2. リードテープ長さ LEAD TAPE LENGTH
- トッパートープ TOP TAPE トッパートープ TOP TAPE
 リーダー部 LEADER PART 未接着部 NON-BONDED PART



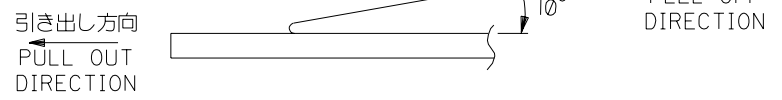
DETAIL "F"



SECT. Z-Z



3. トッパートープの剥離強度：(剥離方向は下図参照)
 0.1N ~ 1.3N(10gf ~ 130gf) 尚、本規格値は、出荷時に適用。
 (但し、輸送時に剥離が発生しない事。)
- PEELING OFF FORCE OF TOP TAPE
 0.1N ~ 1.3N(10gf ~ 130gf) (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
 THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
 PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTATION



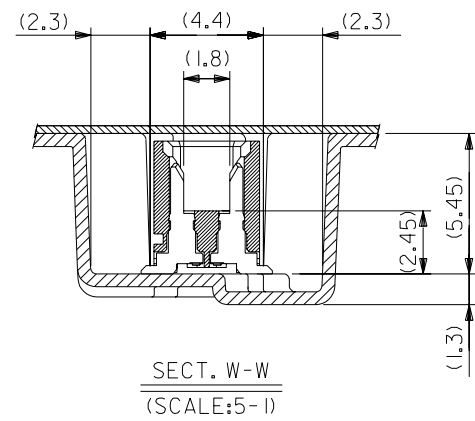
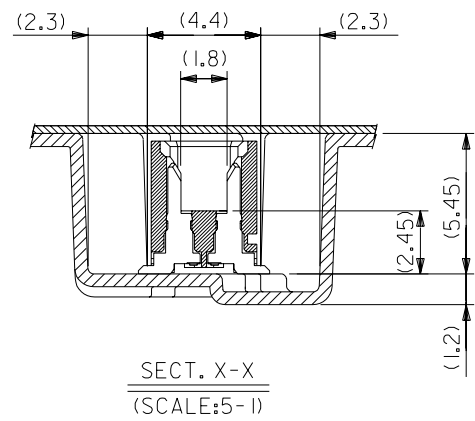
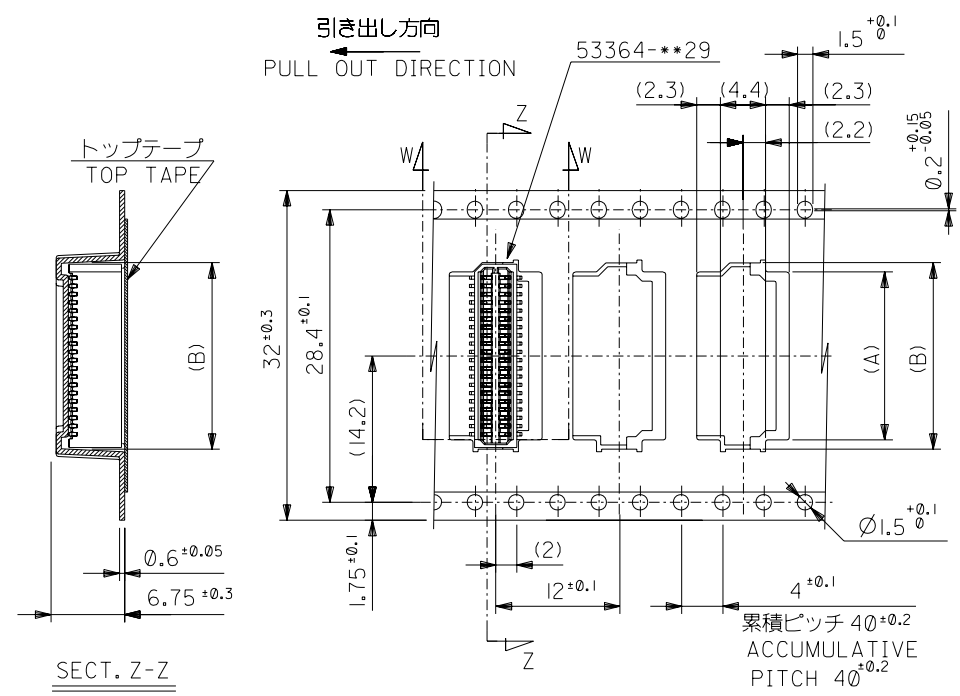
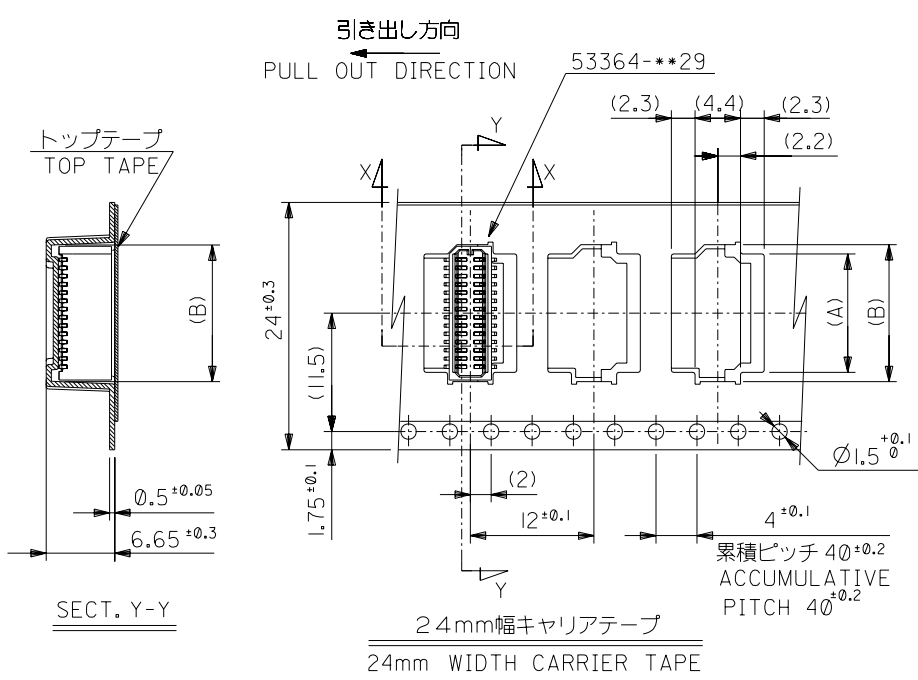
4. 材料 MATERIAL
- キャリアテープ：ポリプロピレン (PP) CARRIER TAPE:POLYPROPYLENE
 トッパートープ：PET, PE, PEF TOP TAPE:PET,PE,PEF
 リール：ポリスチレン (PS) REEL:POLYSTYREN(PS)
 <リサイクル材を含む> <RECYCLE MATERIAL CONTAINED>
5. 本製品は 53364-**-91 の鉛フリー品である。
 THIS PRODUCT IS LEAD FREE OF 53364-**-91.

16	17.5	9.3	7.5	53364-1871	18
		6.9	5.1	53364-1271	12
		6.1	4.3	53364-1071	10
キャリアテープ幅 CARRIER TAPE WIDTH	C (B)	(A)	MATERIAL. NO.	極数 CIRCUIT	

角度 ANGLE	±3°
30以上 OVER	±0.3
10以上 30未満 OVER 30 UNDER	±0.25
未済 UNDER	±0.2
一般公差 GENERAL TOLERANCES	
記号 LTR	0 新規作成 (J2004-1478) RELEASED
変更内容 REVISION RECORD	MN KT
日付 DATE	03/12/11
DR. CHK.	M. NINOMIYA K. TOJO
APP'D BY	M. SASAO
尺度 SCALE	—

材料 MATERIAL 注記参照 SEE NOTES	molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社
仕上げ FINISH	—
適用電線範囲 WIRE RANGE	—
被覆外径 INS. RANGE	—
DRAWN BY '03/12/11 M. NINOMIYA	CHK'D BY '03/12/11 K. TOJO
APP'D BY '03/12/11 M. SASAO	尺度 SCALE —
DWG. NO. (SHEET 1 OF 2) SD-53364-**-71	REV 0

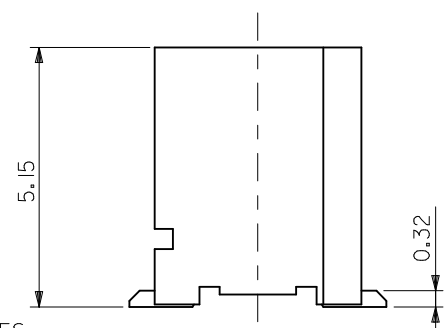
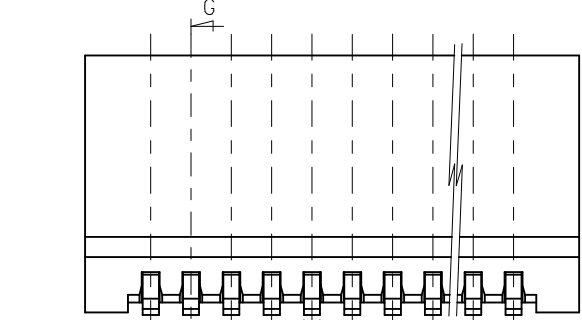
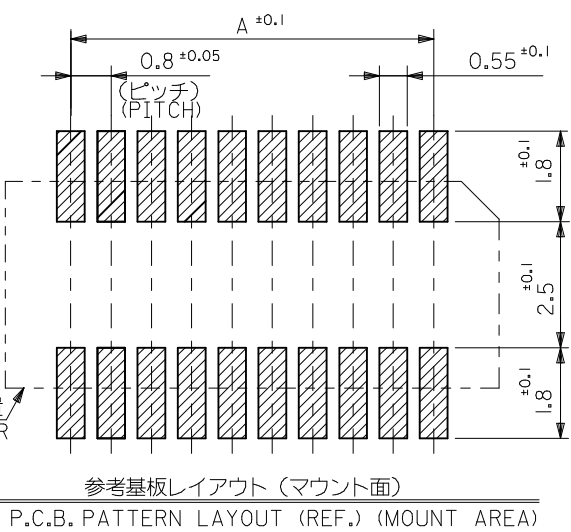
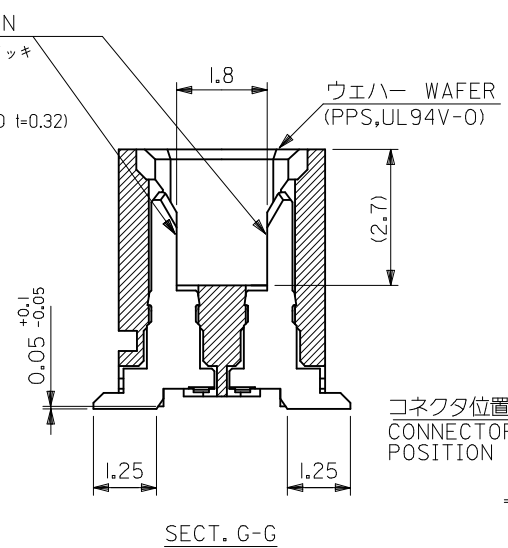
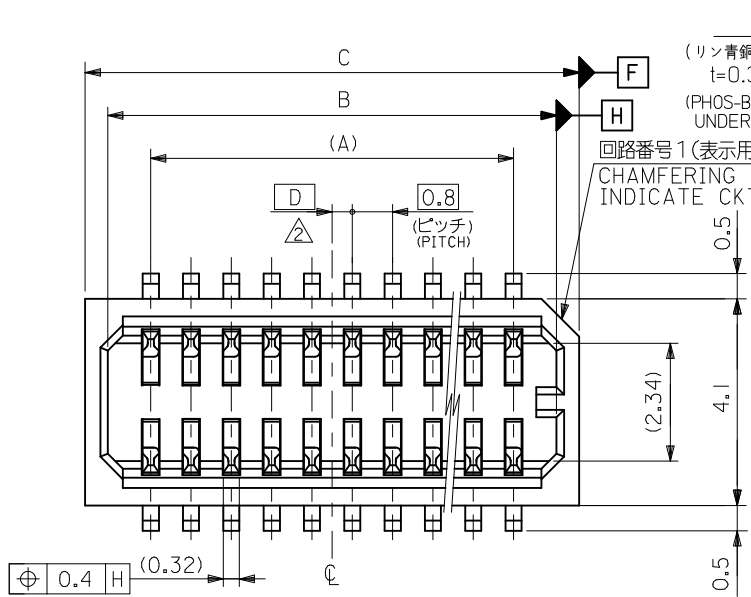
MM DIMENSIONS IN METRIC DO NOT SCALE DRAWING



32	33.5	18.9	17.1	53364-4271	42
		18.1	16.3	53364-4071	40
24	25.5	16.5	14.7	53364-3671	36
		14.1	12.3	53364-3071	30
		13.3	11.5	53364-2871	28
		10.1	8.3	53364-2071	20
キャリアテープ幅 CARRIER TAPE WIDTH	C	(B)	(A)	MATERIAL NO.	極数 CIRCUIT

材料 MATERIAL	SHEET 1 OF 2 参照 REFER TO SHEET 1 OF 2		molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
仕上げ FINISH	—#—		REVISE ONLY ON CAD SYSTEM	
適用電線範囲 WIRE RANGE	—#—		TITLE 名称	
被覆外径 INS. RANGE	—#—		0.8 BtB Conn Wafer Assy ST SMT Without Boss Embstp Pkg -LEAD FREE-	
DRAWN BY '03/12/11 M.NINOMIYA	CHK'D BY '03/12/11 K.TOJO	DR. '03/12/11 M.SASAO	尺度 SCALE	—#—
DWG. NO. (SHEET 2 OF 2) SD-53364-**-71	REV 0			

角度 ANGLE	±30°
30 以上 OVER	±0.3
10 以上 30 未満 OVER 30 UNDER	±0.25
未満 10 UNDER	±0.2
一般公差 GENERAL TOLERANCES	

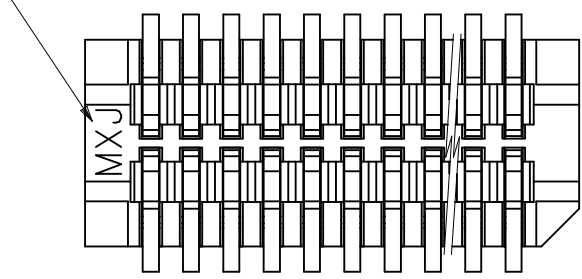


注記 NOTES

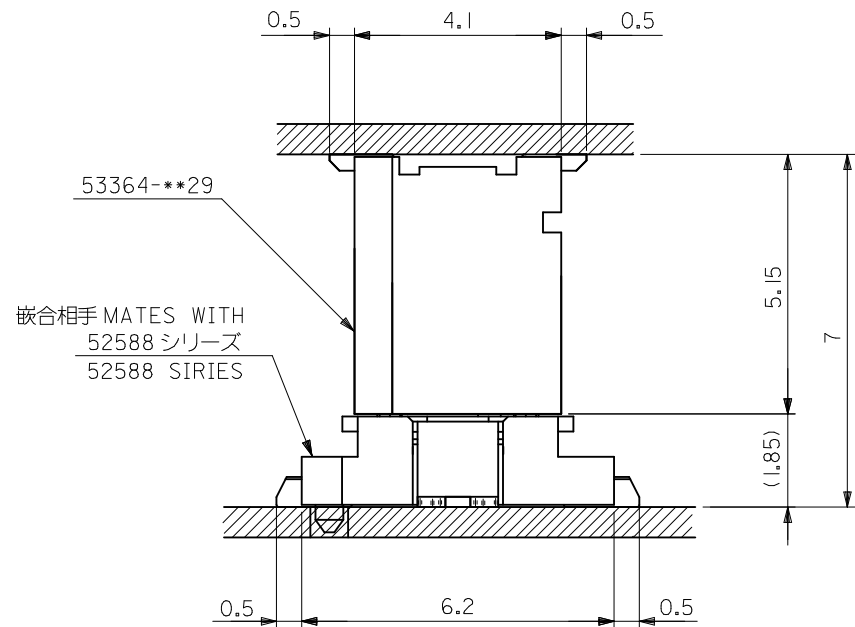
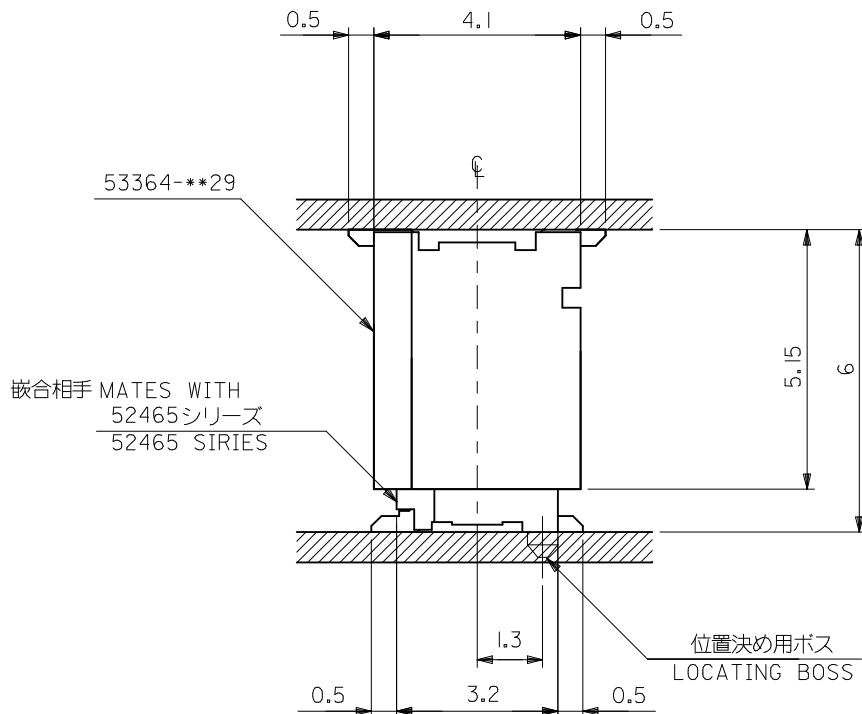
1. 嵌合相手 : 52465, 52588 シリーズ
 MATES WITH : 52465, 52588 SERIES
2. ウェハーの ϕ から隣接するピンの ϕ 迄の位置を示す。
 SHOW POSITION FROM ϕ OF WAFER TO ϕ OF ADJACENT PINS.
3. 本製品は 53364-**-27 の鉛フリー品である。
 THIS PRODUCT IS LEAD FREE OF 53364-**-27.

0.4	17.8	16.9	15.2	53364-4029	40
0.4	16.2	15.3	13.6	53364-3629	36
0.8	13.8	12.9	11.2	53364-3029	30
0.4	13.0	12.1	10.4	53364-2829	28
0.4	9.8	8.9	7.2	53364-2029	20
0.8	9.0	8.1	6.4	53364-1829	18
0.4	6.6	5.7	4.0	53364-1229	12
0.8	5.8	4.9	3.2	53364-1029	10
D	C	B	A	MATERIAL. NO.	極数 CKT.

トレードマーク TRADE MARK



REVISED EC NO: J2009-1121 DRWN: MAKURAA 2008/12/15 CHKD: T. HARUYAMA 2008/12/15 APPR: NUKITA 2009/01/13	DESCRIPTION GENERAL TOLERANCES (UNLESS SPECIFIED) 10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3 ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	TITLE 0.8 BOARD TO BOARD CONN. WAFER ASSY ST. SMT -LEAD FREE- MOLEX INCORPORATED DOCUMENT NO. SD-53364-003 SHEET NO. 1 OF 2
		DRAWN BY M. NINOMIYA	DATE '03/12/11	THIRD ANGLE PROJECTION	
		CHECKED BY K. TOJO	DATE '03/12/11	MATERIAL NO. SEE TABLE	
		APPROVED BY M. SASAO	DATE '03/12/11	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	



嵌合状態図 (参考)
MATED DRAWING (REF.)

REVISED EC NO: J2009-1121 DRWN: KAKURAA 2008/12/15 CHKD: T. HARUYAMA 2008/12/15 APPR: NUKITA 2009/01/13	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± ---	DRAWN BY M. NINOMIYA	DATE '03/12/11	TITLE 0.8 BOARD TO BOARD CONN. WAFER ASSY ST. SMT -LEAD FREE-	
	10 OVER 30 UNDER	± ---	CHECKED BY K. TOJO	DATE '03/12/11		
	30 OVER	± ---	APPROVED BY M. SASAO	DATE '03/12/11	MOLEX INCORPORATED	
DESCRIPTION ANGULAR ± --- ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE SHEET 1		DOCUMENT NO. SD-53364-003		SHEET NO. 2 OF 2	
REV	SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					